# GSV2005 SPECIFIATION

2019-9-23

**GSCOOLINK** 

# 1. General Description

#### 1.1 General Information

The GSV2005 is HDMI1.4/2.0 compatible, HDCP 1.4/2.2 supported, configurable 1-in-4-out splitter device. All 4 outputs are identical on transmitter capability. The HDMI input and output maximum processing pixel clock frequency is 600MHz which means the video resolution can support up to 4kx2k@60Hz 4:4:4 8-bit. The maximum processing audio sample frequency is 192K Hz for non-compression timing. GSV2005 supports HDR10 and Dolby Vision HDR as input and output.

### 1.2 Capability Description

### 1.2.1 HDMI Video Input and Output

Supports 6Gb/s HDMI 2.0 and 1.4 protocol. The video input port can drive 4 video outputs at the same time.

With powerful HDMI Rx equalizer and Tx pre-emphasis capability, GSV2005 can cascade itself (or GSV200x series chips) with at least 7 stages for all HDMI 2.0 timings.

#### 1.2.2 External Interface

There is Inter-Integrated Circuit (I<sup>2</sup>C) as the chip's external interface.

#### 1.2.3 HDCP

There are HDCP 1.4/2.2 encryption and decryption engines separately for HDMI transmitter and receiver. This enables each HDMI transmitter and receiver to be HDCP 1.4/2.2 capable separately.

And there are also built-in HDCP 2.2-to-1.4, 1.4-to-2.2, 2.2-to-2.2, 1.4-to-1.4 repeater engine. That means MCU software will not have heavy workload for repeater processing, even when sinks are of different and mixed types of HDCP protocol.

# 2. Pin Description

### 2.1 Pin Diagram

GSV2005's package is QFNWB124L (1212X0.55-0.35).

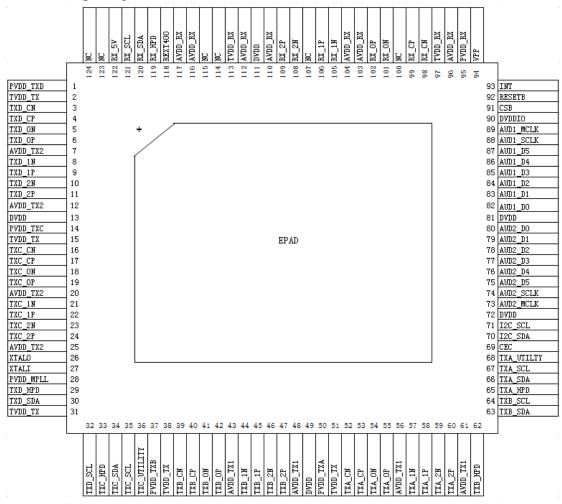


Figure 1. GSV2005 Package

### 2.2 Pin Description

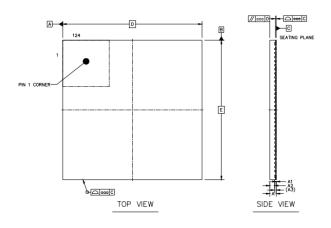
Pin Name	Direction	Pin No.	Description
5V Tolerance Pins			
CEC	I/O	69	5V tolerance CEC PAD
RX_5V	Power	122	RX 5V POWER
RX_HPD	I/O	119	RX 5V tolerance HPD PAD
RX_SDA	I/O	120	RX 5V tolerance DDC SDA PAD
RX_SCL	I	121	RX 5V tolerance DDC SCL PAD
TXA_HPD	I	65	TXA 5V tolerance HPD PAD

# 6. Packaging

# **6.1 Packaging Description**

The GSV2005 device is packaged in a 124-pin, 12mmx12mm QFN package.

## **6.2 Package Dimensions**



		SYMBOL	MIN	NOM	MAX
TOTAL THICKNESS		A	0.5	0.55	0.6
STAND OFF		A1	0	0.02	0.05
MOLD THICKNESS		A2		0.4	
L/F THICKNESS		A3	0.152 REF		
LEAD WIDTH	ь	0.12	0.17	0.22	
BODY SIZE	X	D	12 BSC		
BODT SIZE	Y	E	12 BSC		
LEAD PITCH	e	0.35 BSC			
EP SIZE	x	D2	7.2	7.3	7.4
EP SIZE	Y	E2	7.2	7.3	7.4
LEAD LENGTH	L	0.3	0.4	0.5	
LEAD TIP TO EXPOSED	к	1.95 REF			
PACKAGE EDGE TOLER	000	0.1			
MOLD FLATNESS	ccc	0.1			
COPLANARITY	eee	0.08			
LEAD OFFSET	bbb	0.07			
EXPOSED PAD OFFSET	fff	0.1			

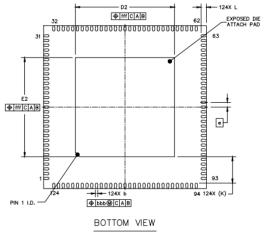


Figure 6. GSV2005 Package Dimensions

